



Attorney Docket No. 0756-7719

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Write Patent Application of:

Shunpei YAMAZAKI et al.

Serial No. 10/581,674

Filed: June 5, 2006

For: METHOD FOR MANUFACTURING  
THIN FILM INTEGRATED CIRCUIT  
DEVICE, NONCONTACT THIN FILM  
INTEGRATED CIRCUIT DEVICE  
AND METHOD FOR  
MANUFACTURING THE SAME, AND  
IDTAG AND COIN INCLUDING THE  
NONCONTACT THIN FILM  
INTEGRATED CIRCUIT

) Group Art Unit: 2823

) Examiner: William D. Coleman

CERTIFICATE OF MAILING

I hereby certify that this correspondence is  
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Commissioner for Patents, P.O. Box 1450,  
Alexandria, VA 22313-1450, on July 7, 2008.

*Adam M. Stamper*

AMENDMENT

Honorable Commissioner of Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In response to the Official Action dated March 5, 2008, please consider the  
following amendments and remarks in connection with the above-identified application.

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims, which begins  
on page 3 of this paper.

**Remarks** begin on page 12 of this paper.